

DESCRIPTION

The HY524400 is the new generation and fast dynamic RAM organized 1,048,576 x 4 bits. The HY524400 utilizes CMOS silicon gate process technology as well as advanced circuit techniques to provide wide operating margins to the users. Multiplexed address inputs permit the HY524400 to be packaged in a standard 20/26 pin plastic SOJ. The package size provides high system bit densities and is compatible with widely available automated-test equipments. System oriented-feature includes single power supply of $5V \pm 10\%$ tolerance and direct interfacing capability with high performance logic families such as Schottky TTL.

FEATURES

- Low power dissipation
Max. CMOS standby 5.5mW
Max. TTL standby 11.0mW
Max. operating

Speed	Power
70	742.5mW
80	632.5mW
10	577.5mW

- Single power supply of $5V \pm 10\%$
- TTL compatible inputs and outputs
- Fast access Time

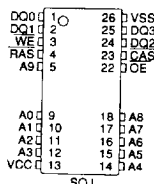
Speed	t _{RAC}	t _{CAC}	t _{PC}
70	70ns	20ns	45ns
80	80ns	20ns	50ns
10	100ns	25ns	60ns

- Fast page mode operation
- Read-Modify-Write capability
- CAS-before-RAS, RAS-only, refresh
- 1024 refresh cycles / 16ms

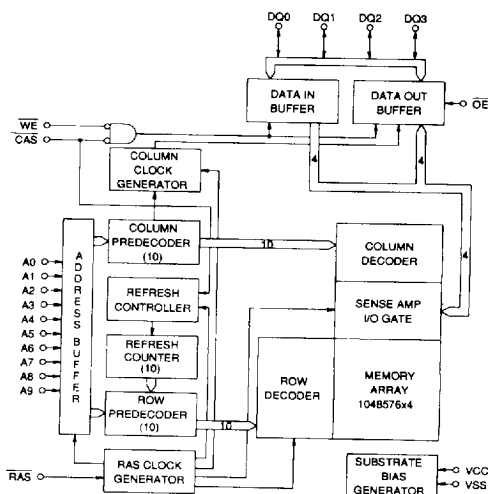
PIN DESCRIPTION

RAS	Row Address Strobe
CAS	Column Address Strobe
WE	Write Enable
OE	Output Enable
A0-A9	Address Input
DQ0-DQ3	Data Input/Output
Vcc	Power (+ 5V)
Vss	Ground

PIN CONNECTION



BLOCK DIAGRAM



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1AC04-10-MAY94

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
TA	Ambient Temperature	0 to 70	°C
TSTG	Storage Temperature	-55 to 125	°C
VIN, VOUT	Voltage on Any Pin Relative to Vss	-0.7 to VCC + 0.7	V
VCC	Voltage on VCC Relative to Vss	-0.5 to 6.5	V
Ios	Short Circuit Output Current	50	mA
PD	Power Dissipation	1.0	W
TSOLDER	Soldering Temperature•Time	260• 10	°C•sec

NOTE : Operation at or above Absolute Maximum Ratings can adversely affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS

(TA= 0°C to 70°C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VCC	Supply Voltage	4.5	5.0	5.5	V
VIH	Input High Voltage	2.4	-	VCC+ 1.0	V
VIL	Input Low Voltage	0.0	-	0.8	V

NOTE : All voltages are referenced to Vss.

Noise on RAS, CAS and WE must be within Application Specification limits.

This can be accomplished with adding in your design a series 33 ohm resistor for the above input near the DRAMs.

DC CHARACTERISTICS

(TA= 0°C to 70°C, VCC= 5V± 10%, VSS= 0V, unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS	SPEED	MIN.	MAX.	UNIT	NOTE
ILI	Input Leakage Current (Any Input Pins)	VSS ≤ VIN ≤ 6.5V, All other pins not under test= VSS		-10	10	μA	
ILO	Output Leakage Current (High Impedance State)	VSS ≤ VOUT ≤ 5.5V, RAS & CAS at VIH		-10	10	μA	
ICC1	VCC Supply Current, Operating	tRC= tRC (min.)	70	-	135	mA	1,2,3
			80	-	115		
			10	-	105		
ICC2	VCC Supply Current, TTL Standby	RAS & CAS at VIH		-	2	mA	
ICC3	VCC Supply Current, RAS-only refresh	tRC= tRC (min.)	70	-	135	mA	1,3
			80	-	115		
			10	-	105		
ICC4	VCC Supply Current, Fast Page mode	tPC= tPC (min.)	70	-	65	mA	1,2,3
			80	-	60		
			10	-	50		
ICC5	VCC Supply Current, CMOS Standby	RAS & CAS ≤ VCC-0.2V		-	1	mA	
ICC6	VCC Supply Current, CAS-before-RAS refresh	tRC= tRC (min.)	70	-	135	mA	1,3
			80	-	115		
			10	-	105		
VOL	Output Low Voltage	IOL= 4.2mA		-	0.4	V	
VOH	Output High Voltage	IOH= -5mA		2.4	-	V	

NOTE :

1. ICC1, ICC3, ICC4, and ICC6 depend on cycle rate.
2. ICC1 and ICC4 depend on output loading. Specified values are obtained with the output open.
3. It depends on user whether column address is changed or not at least once while RAS= VIL and CAS= VIH.

AC CHARACTERISTICS

(TA= 0°C to 70°C, VCC= 5V± 10%, VSS= 0V, unless otherwise noted.) NOTE : 1, 2, 3

(TA= 0°C to 70°C, VCC= 5V± 10%, VSS= 0V, unless otherwise noted.) NOTE 1, 2, 3										
#	SYMBOL	PARAMETER	-70		-90		-10		UNIT	NOTE
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	tRC	Random Read or Write Cycle Time	130	-	150	-	180	-	ns	3
2	tRWC	Read-Modify-Write Cycle Time	180	-	205	-	245	-	ns	3,11
3	tPC	Fast Page Mode Cycle Time	45	-	50	-	60	-	ns	3
4	tPRWC	Fast Page Mode Read-Modify-Write Cycle Time	90	-	100	-	115	-	ns	3,11
5	tRAC	Access Time from RAS	-	70	-	80	-	100	ns	4,5,6
6	tCAC	Access Time from CAS	-	20	-	20	-	25	ns	4,5,6
7	tAA	Access Time from Column Address	-	35	-	40	-	50	ns	5,6
8	tCPA	Access Time from CAS Precharge	-	40	-	45	-	55	ns	6
9	tCLZ	CAS to Output Low Impedance	0	-	0	-	0	-	ns	8
10	tOFF	Output Buffer Turn-off Delay	0	15	0	15	0	20	ns	
11	tT	Transition Time (Rise and Fall)	3	50	3	50	3	50	ns	
12	tRP	RAS Precharge Time	50	-	60	-	70	-	ns	
13	tRAS	RAS Pulse Width	70	16K	80	16K	100	16K	ns	3
14	tRASP	RAS Pulse Width (Fast Page Mode)	70	16K	80	16K	100	16K	ns	
15	tRSH	RAS Hold Time	20	-	20	-	25	-	ns	
16	tCSH	CAS Hold Time	70	-	80	-	100	-	ns	
17	tCAS	CAS Pulse Width	20	-	20	-	25	-	ns	
18	tRCD	RAS to CAS Delay	20	50	20	60	20	75	ns	4
19	tRAD	RAS to Column Address Delay Time	15	-	15	-	17	-	ns	7
20	tCRP	CAS to RAS Precharge Time	10	-	10	-	10	-	ns	
21	tCP	CAS Precharge Time	10	-	10	-	10	-	ns	
22	tASR	Row Address Set-up Time	0	-	0	-	0	-	ns	
23	tRAH	Row Address Hold Time	10	-	10	-	15	-	ns	
24	tASC	Column Address Set-up Time	0	-	0	-	0	-	ns	
25	tCAH	Column Address Hold Time	15	-	15	-	20	-	ns	
26	tAR	Column Address Hold Time from RAS	50	-	55	-	70	-	ns	
27	tRAL	Column Address to RAS Lead Time	35	-	40	-	50	-	ns	
28	tRCS	Read Command Set-up Time	0	-	0	-	0	-	ns	
29	tRCH	Read Command Hold Time Referenced to CAS	0	-	0	-	0	-	ns	
30	tRRH	Read Command Hold Time Referenced to RAS	0	-	0	-	0	-	ns	
31	tWCH	Write Command Hold Time	15	-	15	-	20	-	ns	
32	tWCR	Write Command Hold Time from RAS	55	-	60	-	65	-	ns	
33	tWP	Write Command Pulse Width	15	-	15	-	20	-	ns	
34	tRWL	Write Command to RAS Lead Time	20	-	20	-	25	-	ns	
35	tCWL	Write Command to CAS Lead Time	20	-	20	-	25	-	ns	
36	tDS	Data-In Set-up Time	0	-	0	-	0	-	ns	9
37	tDH	Data-In Hold Time	15	-	15	-	20	-	ns	9
38	tDHR	Data-In Hold Time Referenced to RAS	55	-	60	-	65	-	ns	
39	tREF	Refresh Period (1024 cycles)	-	16	-	16	-	16	ms	2,3
40	tWCS	Write Command Set-up Time	0	-	0	-	0	-	ns	

AC CHARACTERISTICS

(continued)

Continued

#	SYMBOL	PARAMETER	HY524400J						UNIT	NOTE
			-70		-80		-10			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
41	tCWD	CAS to WE Delay Time	40	-	45	-	55	-	ns	11
42	tRWD	RAS to WE Delay Time	90	-	105	-	130	-	ns	11
43	tAWD	Column Address to WE Delay Time	55	-	65	-	80	-	ns	11
44	tCSR	CAS Set-up Time (CBR Cycle)	10	-	10	-	10	-	ns	10
45	tCHR	CAS Hold Time (CBR Cycle)	15	-	20	-	20	-	ns	
46	tRPC	RAS to CAS Precharge Time	10	-	10	-	10	-	ns	
47	tROH	RAS Hold Time Referenced to OE	10	-	10	-	15	-	ns	
48	tOEA	OE Access Time	-	20	-	20	-	25	ns	5,6
49	tOED	OE to Data Delay	20	-	20	-	25	-	ns	
50	tOEZ	Output Buffer Turn Off Delay Time from OE	-	15	-	15	-	20	ns	8
51	tOEH	OE Command Hold Time	15	-	15	-	20	-	ns	
52	tCPWD	WE Delay Time from CAS Precharge	65	-	70	-	80	-	ns	
53	tRHCP	RAS Hold Time from CAS Precharge	35	-	40	-	45	-	ns	
54	tWRP	WE to RAS Precharge Time (CBR Cycle)	5	-	5	-	5	-	ns	10
55	tWRH	WE to RAS Hold Time (CBR Cycle)	10	-	10	-	15	-	ns	10

NOTE :

1. An initial pause of at least 500 μ s is required after power-up followed by 8 RAS cycles before proper device operation is achieved. These must be either RAS-only or CAS-before-RAS refresh cycles. After the initialization cycles the DRAM is ready for normal use.
2. 1024 refreshes are required every 16ms. A burst of eight consecutive refreshes are allowed to keep tRAS= 16ms average.
3. All AC timings assume tT(max.)= 5ns. If the actual tT is greater than tT(max.), then the cycle times need to be greater than that specified by the amount each transition exceeds tT(max.). HY524400 will support a tT up to 50ns. The transition time is defined between the VIH and VIL. All timings are referenced to a VIL or VIH.
4. tRCD(max.) is specified as a reference point only. If tRCD> tRCD(max.), then this parameter is increased by the amount exceeds tRCD(max.)
5. tRAC, tCAC, tAA and tOEA must be satisfied to guarantee access. Please check that all parameters are met for your application.
6. Access assumes a load equivalent to 100pF.
7. tRAD is specified as a reference point only. If tRAD> tRAC-tAA, then the access is increased by the difference.
8. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to the output voltage levels.
9. Data in set-up and holds are measured from the later of falling signal CAS or WE.
10. tCP, tCSR, tWRP and tWRH all need to be valid for CBR users.
11. A 5ns delta is used between data reaching high impedance and having valid data in for these numbers.

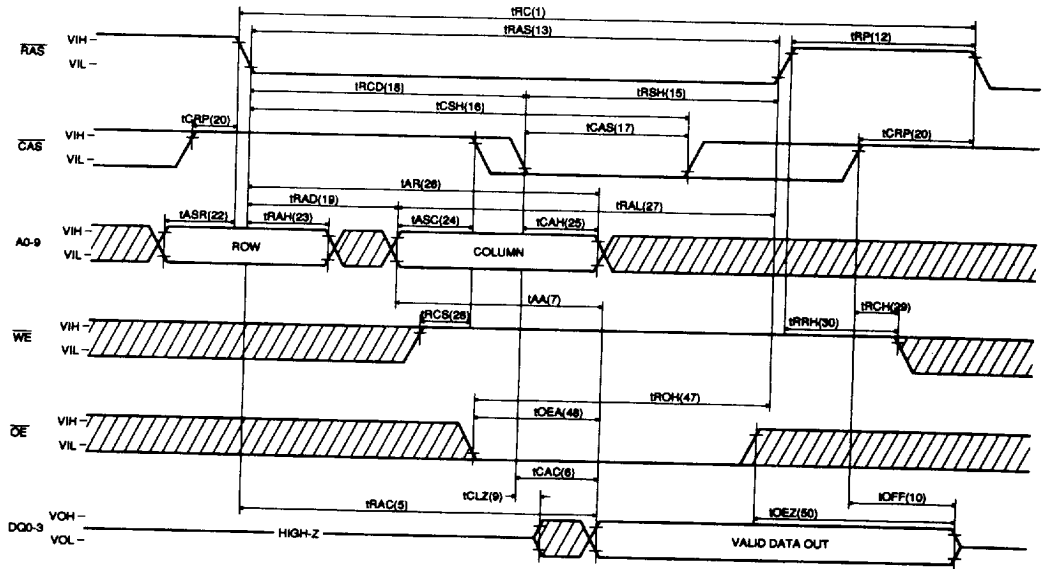
CAPACITANCE

(TA= 25°C, VCC= 0V $\pm$ 10%, VSS= 0V, f= 1MHz, unless otherwise noted.)

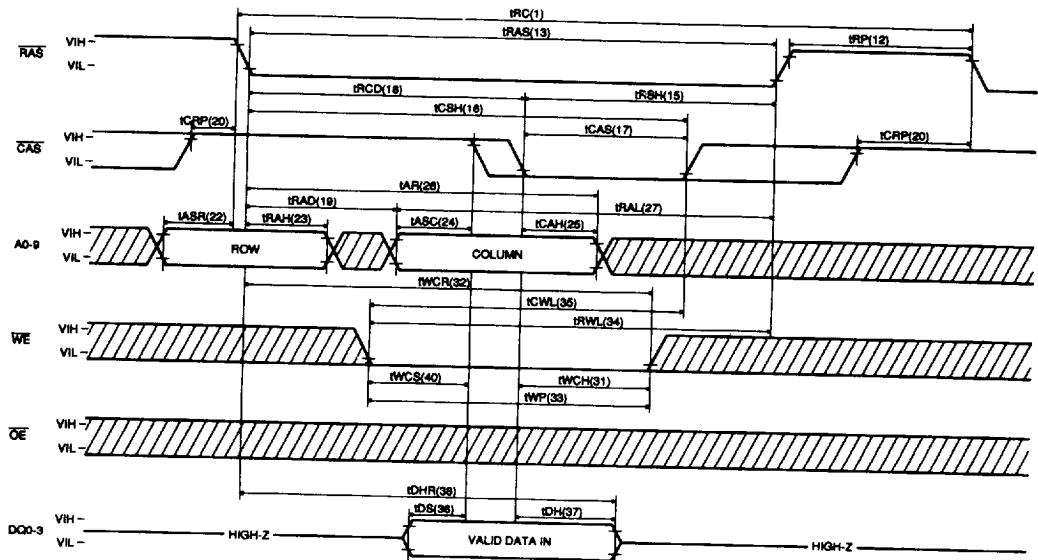
SYMBOL	PARAMETER	TYP.	MAX.	UNIT
CIN1	Input Capacitance (A0-A9, D)	-	5	pF
CIN2	Input Capacitance (RAS, CAS, WE, OE)	-	5	pF
COUT	Output Capacitance (Q)	-	8	pF

TIMING DIAGRAM

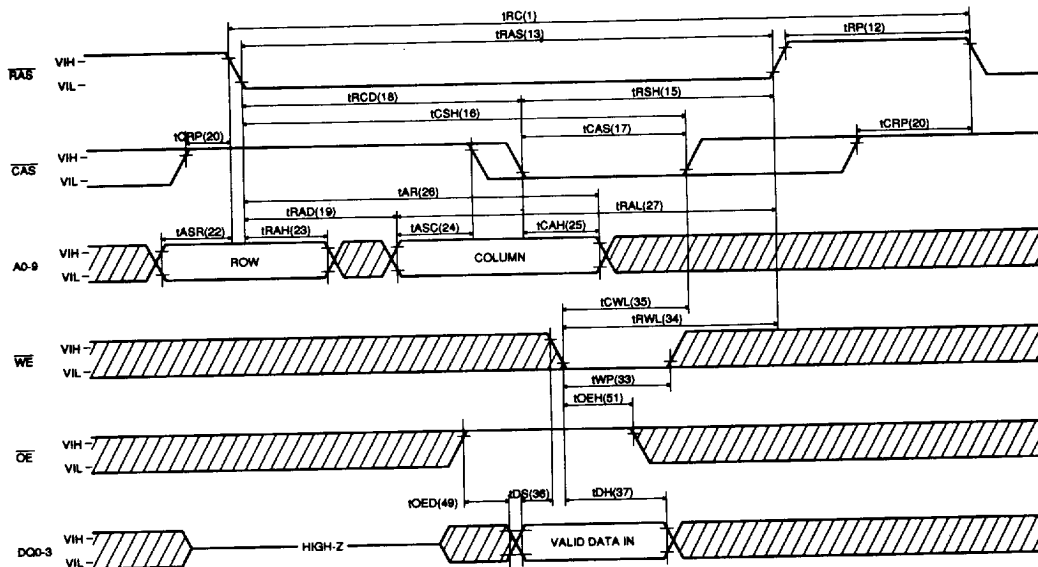
READ CYCLE



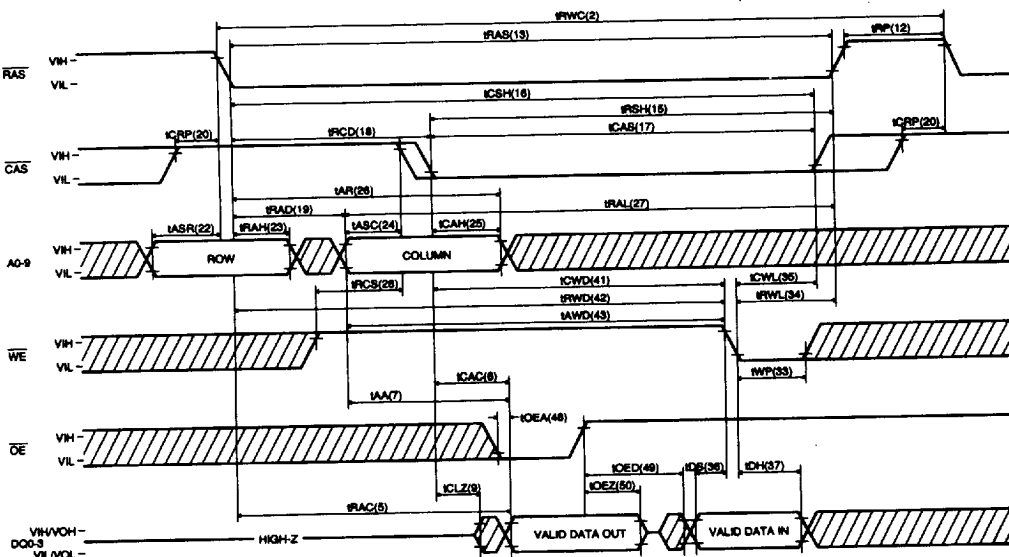
EARLY WRITE CYCLE



WRITE CYCLE (OE CONTROLLED WRITE)



READ-MODIFY-WRITE CYCLE

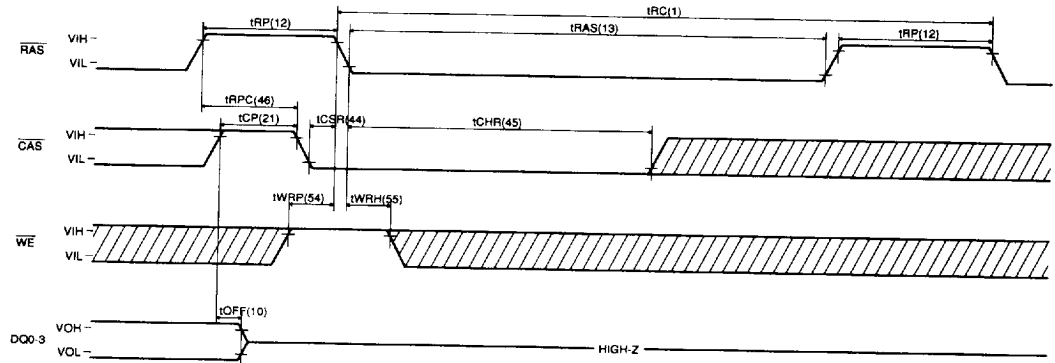


The timing diagram for the 64K1602 shows the following signals and parameters:

- RAS:** RAS Enable signal. Parameters: $t_{CRP}(20)$, $t_{RCD}(18)$, $t_{CSH}(18)$, $t_{CAS}(17)$, $t_{CP}(21)$, $t_{PC}(3)$, $t_{RSH}(15)$, $t_{CAS}(17)$, $t_{RP}(12)$.
- CAS:** CAS Enable signal. Parameters: $t_{RAD}(19)$, $t_{RAH}(23)$, $t_{ASC}(24)$, $t_{CAH}(25)$, $t_{RAL}(27)$.
- A0-9:** Address bus. Parameters: $t_{ASB}(22)$, $t_{CAH}(25)$, $t_{ASC}(24)$, $t_{CAH}(25)$, $t_{ASC}(24)$, $t_{CAH}(25)$.
- WE:** Write Enable signal. Parameters: $t_{WCS}(40)$, $t_{WCH}(31)$, $t_{WIP}(33)$, $t_{WCR}(32)$, $t_{OE}(51)$.
- OE:** Output Enable signal. Parameters: $t_{OE}(51)$, $t_{OE}(49)$.
- DQ0-9:** Data bus. Parameters: $t_{DS}(36)$, $t_{DH}(37)$, $t_{OE}(49)$.

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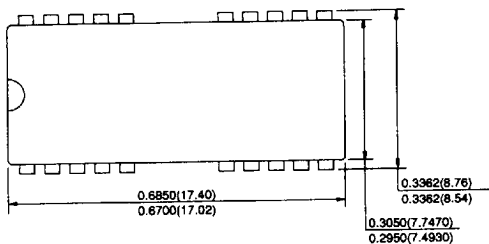
CAS-BEFORE-RAS REFRESH CYCLE



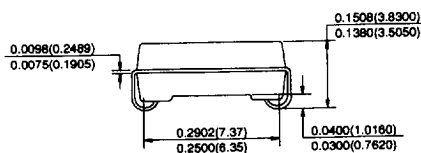
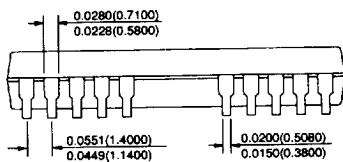
NOTE : A0-9 and OE = "H" or "L"

PACKAGE INFORMATION

300 mil 20/26 pin Small Outline J-form Package (J)



UNIT : INCH(mm)



ORDERING INFORMATION

PART NO	SPEED	POWER	PACKAGE
HY524400J	70/80/10		SOJ